



Material Content Data Sheet



Sales Product Name		IFX1050G VIO		Issued		29. August 2013		
MA#		MA000981498						
Package		PG-DSO-8-3		Weight*		83.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.700	4.43	4.43	44326	44326
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111	
	non noble metal	zinc	7440-66-6	0.037	0.04		444	
	non noble metal	iron	7439-89-6	0.742	0.89		8885	
wire	non noble metal	copper	7440-50-8	30.114	36.08	37.02	360758	370198
	noble metal	gold	7440-57-5	0.172	0.21	0.21	2065	2065
	encapsulation	organic material	carbon black	1333-86-4	0.137	0.16		1641
plastics	plastics	epoxy resin	-	5.343	6.40		64004	
	inorganic material	silicondioxide	60676-86-0	40.185	48.14	54.70	481399	547044
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9750	9750
plating	noble metal	silver	7440-22-4	0.541	0.65	0.65	6486	6486
glue	plastics	epoxy resin	-	0.294	0.35		3523	
	noble metal	silver	7440-22-4	1.386	1.66	2.01	16608	20131
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com